

# EAST text search notes

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	337	257/773.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:20
L1	226	257/698.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:07
S1	16	(test or testing or probe) near2 (socket or housing or package or carrier or tray) same (spring) near2 (contact or contacting or electrode or terminal) same (clamp or clamping or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:05
S32	55	(board or card or socket or carrier or substrate) and (spring or coil or elastic or compressible) near (via or aperture or hole or throughhole or thruhole or opening or viahole) near8 (uncoiled or serpentine or S or leaf) near10 (contact or pad or electrode or terminal or wiring or trace or bga or ball near grid or solder near ball or pin or solder near bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:05
S31	303	(test or testing or temporary or probe or burn-in) near2 (board or card or socket or carrier or substrate) and (spring or coil or elastic or compressible) near (via or aperture or hole or throughhole or thruhole or opening or viahole) and (spring or coil or elastic or compressible) near2 (contact or pad or electrode or terminal or wiring or trace or bga or ball near grid or solder near ball or pin or solder near bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:03
S30	42	(test or testing or temporary or probe or burn-in) near2 (board or card or socket) and (spring or coil) near4 (via or aperture or hole or throughhole or thruhole or opening or viahole) near4 (trace or sidewall or plated or plating or lined or wall or edge) near4 (spring or coil)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 14:56
S29	382	(test or testing or temporary or probe or burn-in) near2 (board or card or socket) and (bga or ball near grid or solder near ball or pin or contact or pad or terminal) near3 (spring or coil) near4 (via or aperture or hole or throughhole or thruhole or opening or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 14:47
S28	534	(test or testing or temporary or probe or burn-in) near2 (board or card or socket) and (bga or ball near grid or solder near ball or pin or contact or pad or terminal) near3 (spring) near8 (via or aperture or hole or throughhole or thruhole or opening or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:42
S27	47	(socket or housing or package or carrier or tray) near3 (ic or chip or die) and (solder near ball or ball near grid) near2 spring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:38
S4	45	(socket or housing or package or carrier or tray) near3 (ic or chip or die) and (solder near ball or ball near grid) near2 spring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:28
S26	112	(test or testing or probe or temporary or burn-in) near2 (socket or housing or package or carrier or tray) near3 (ic or chip or die) and (chip or ic or die) near3 (electrode or terminal or contact or solder near ball or ball near grid or bga) near5 (spring) and (clamp or clamping or lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:12
S2	108	(test or testing or probe or temporary or burn-in) near2 (socket or housing or package or carrier or tray) near3 (ic or chip or die) and (chip or ic or die) near3 (electrode or terminal or contact or solder near ball or ball near grid or bga) near5 (spring) and (clamp or clamping or lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:12

S25	97	439/77.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:00
S24	383	439/67.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 13:00
S23	210	324/765.cor. and spring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:34
S22	1566	324/765.cor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:16
S21	95	361/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:16
S20	106	361/769.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 11:03
S19	87	257/785.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:36
S12	87	257/785.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:28
S18	113	257/727.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:19
S11	112	257/727.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:18
S17	42	257/710.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:15
S10	42	257/710.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:15
S16	13	"5199879".pn. "6200143".pn. "6374487".pn. "6428328".pn. "6471524".pn. "6512388".pn. "20020016090"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:09

S15	57	438/117.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:07
S7	53	438/117.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:07
S14	269	438/15.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 10:04
S6	262	438/15.ccor.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 09:42
S13	16	(test or testing or probe) near2 (socket or housing or package or carrier or tray) same (spring) near2 (contact or contacting or electrode or terminal) same (clamp or clamping or lid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 09:41

# EAST interference search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	93	((chip or die or ic or device) near2 (lead or pad or contact or electrode or terminal or trace) near2 (coil or spring)).clm.	US-PGPUB	OR	ON	2005/10/25 10:28
L6	26	((chip or die or ic or device) near2 (lead or pad or contact or electrode or terminal or trace) near5 (coil or spring) and (coil or spring) near2 (opening or aperture or hole or via or viahole or recess or recessed)).clm.	US-PGPUB	OR	ON	2005/10/25 10:29
L8	57	((test or temporary or testing or probe or non-permanent) near3 (socket or card or substrate or board or housing or mounting or carrier or package or packaging) and (spring or coil) near (contact or wiring or contacting)).clm.	US-PGPUB	OR	ON	2005/10/25 10:32
L9	0	((test or temporary or testing or probe or non-permanent) near3 (socket or card or substrate or board or housing or mounting or carrier or package or packaging) and (spring or coil) near2 (ball near grid or solder near ball or bga)).clm.	US-PGPUB	OR	ON	2005/10/25 10:32
L10	2	((coil or coiled) near3 (contact or contacting or trace or pad or terminal or bga or ball near grid or solder near ball or pin or electrode or lead) and (uncoiled or serpentine or leaf or s) near5 (aperture or hole or via or trench or feedthrough or feedthru or viahole or opening)).clm.	US-PGPUB	OR	ON	2005/10/25 10:34
L14	34	((uncoiled or serpentine or leaf or s) near3 (spring or elastic) near3 (aperture or hole or via or trench or feedthrough or feedthru or viahole or opening) and (ic or chip or die or device)).clm.	US-PGPUB	OR	ON	2005/10/25 10:35